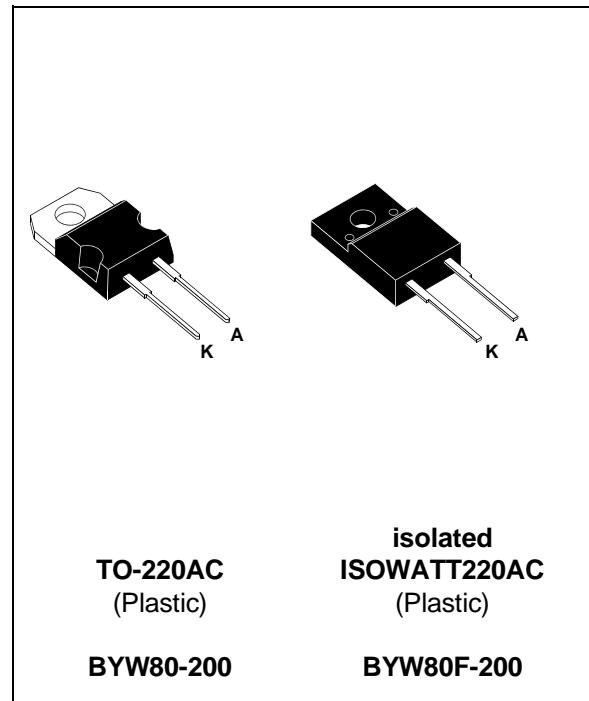


HIGH EFFICIENCY FAST RECOVERY RECTIFIER DIODES

FEATURES

- SUITED FOR SMPS
- VERY LOW FORWARD LOSSES
- NEGLIGIBLE SWITCHING LOSSES
- HIGH SURGE CURRENT CAPABILITY
- HIGH AVALANCHE ENERGY CAPABILITY
- INSULATED VERSION (ISOWATT220AC) :
 - Insulating voltage = 2000 V DC
 - Capacitance = 12 pF



DESCRIPTION

Single chip rectifier suited for switchmode power supply and high frequency DC to DC converters. Packaged in TO-220AC, or ISOWATT220AC this device is intended for use in low voltage, high frequency inverters, free wheeling and polarity protection applications.

ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter			Value	Unit
$I_{F(RMS)}$	RMS forward current			20	A
$I_{F(AV)}$	$\delta = 0.5$	TO-220AC	$T_c=120^\circ\text{C}$	10	A
		ISOWATT220AC	$T_c=95^\circ\text{C}$	10	
I_{FSM}	Surge non repetitive forward current		$t_p=10\text{ms}$ sinusoidal	100	A
T_{stg} T_j	Storage and junction temperature range			- 65 to + 150 - 65 to + 150	$^\circ\text{C}$ $^\circ\text{C}$

Symbol	Parameter	Value	Unit
V_{RRM}	Repetitive peak reverse voltage	200	V

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THERMAL RESISTANCE

Symbol	Parameter	Value	Unit
R _{th} (j-c)	Junction to case	2.5	°C/W
		4.7	

ELECTRICAL CHARACTERISTICS STATIC CHARACTERISTICS

Symbol	Test Conditions		Min.	Typ.	Max.	Unit
I _R *	T _j = 25°C	V _R = V _{RRM}			10	μA
	T _j = 100°C				1	mA
V _F **	T _j = 125°C	I _F = 7 A			0.85	V
	T _j = 125°C	I _F = 15 A			1.05	
	T _j = 25°C	I _F = 15 A			1.15	

Pulse test : * tp = 5 ms, duty cycle < 2 %

** tp = 380 μs, duty cycle < 2 %

To evaluate the conduction losses use the following equation :

$$P = 0.65 \times I_{F(AV)} + 0.027 \times I_{F}^2(RMS)$$

RECOVERY CHARACTERISTICS

Symbol	Test Conditions		Min.	Typ.	Max.	Unit
trr	T _j = 25°C	I _F = 0.5A	I _{rr} = 0.25A		25	ns
		I _R = 1A			35	
tfr	T _j = 25°C	I _F = 1A V _{FR} = 30V	dI _F /dt = -50A/μs		15	ns
V _{FP}	T _j = 25°C	I _F = 1A	tr = 10 ns		2	V
		V _{FR} = 1.1 x V _F				

Fig.1 : Average forward power dissipation versus average forward current.

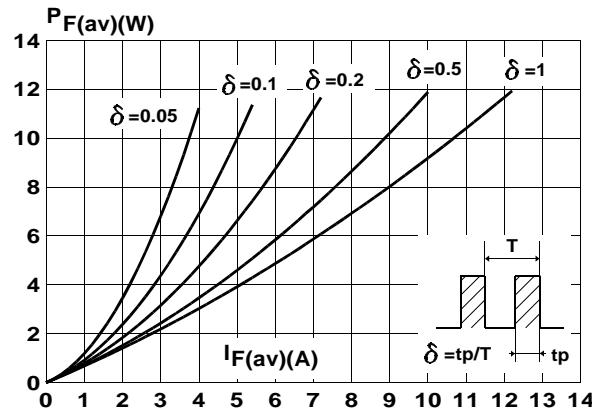


Fig.2 : Peak current versus form factor.

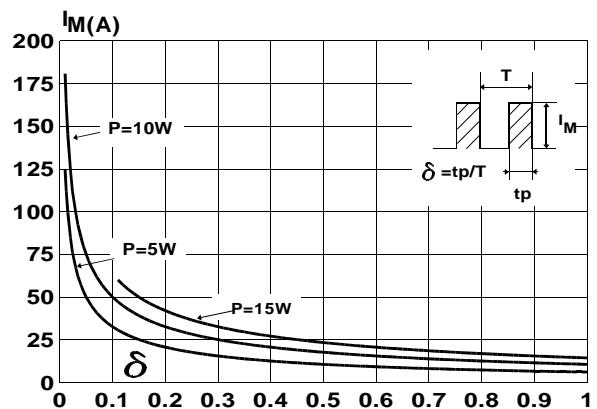


Fig.3 : Forward voltage drop versus forward current (maximum values).

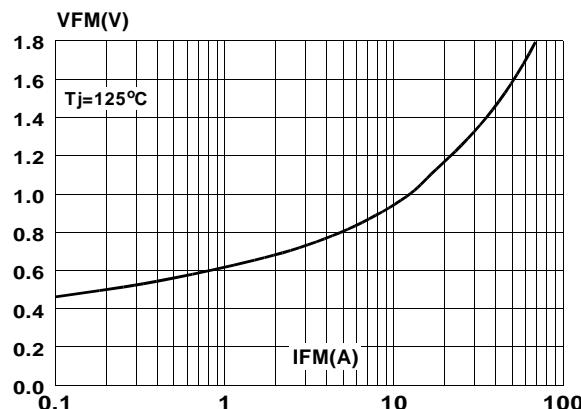


Fig.4 : Relative variation of thermal impedance junction to case versus pulse duration.
(TO-220AC)

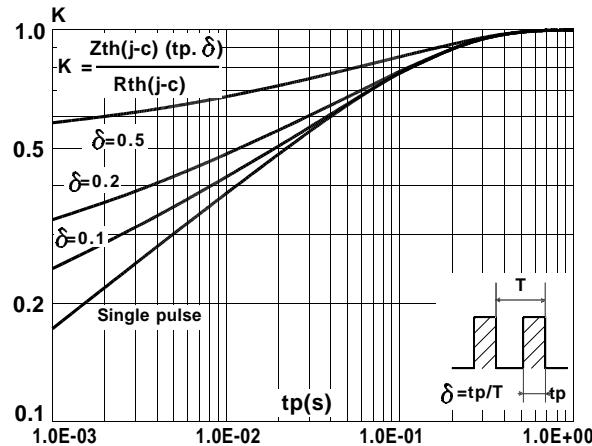
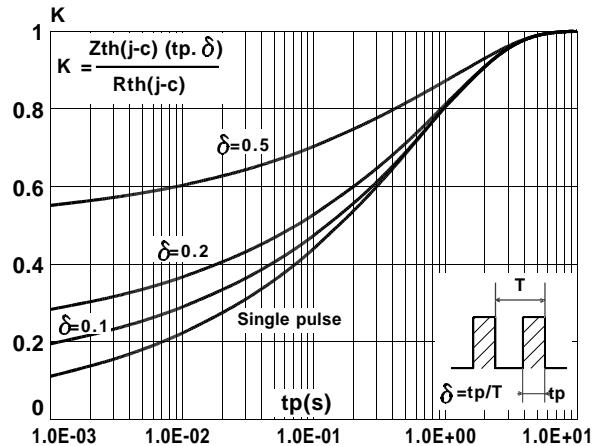


Fig.5 : Relative variation of thermal impedance junction to case versus pulse duration.
(ISOWATT220AC)



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Fig.6 : Non repetitive surge peak forward current versus overload duration.
(TO-220AC)

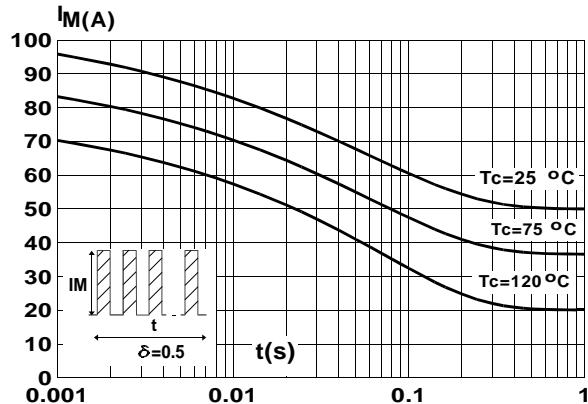


Fig.8 : Average current versus ambient temperature.
(duty cycle : 0.5) (TO-220AC)

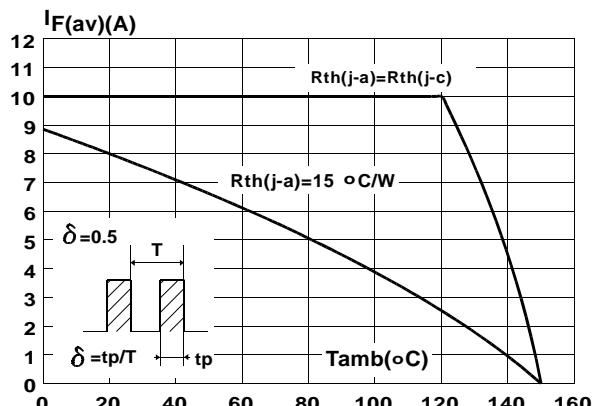


Fig.10 : Junction capacitance versus reverse voltage applied (Typical values).

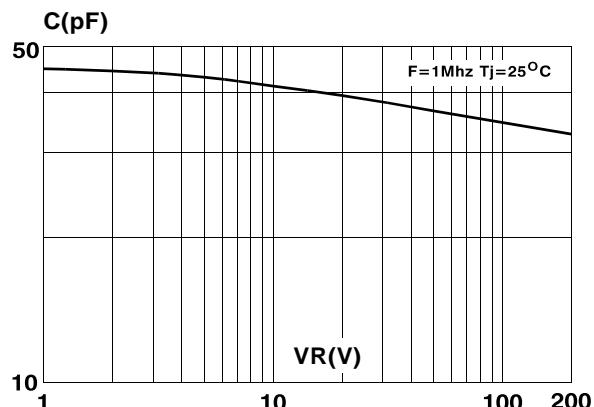


Fig.7 : Non repetitive surge peak forward current versus overload duration.
(ISOWATT220AC)

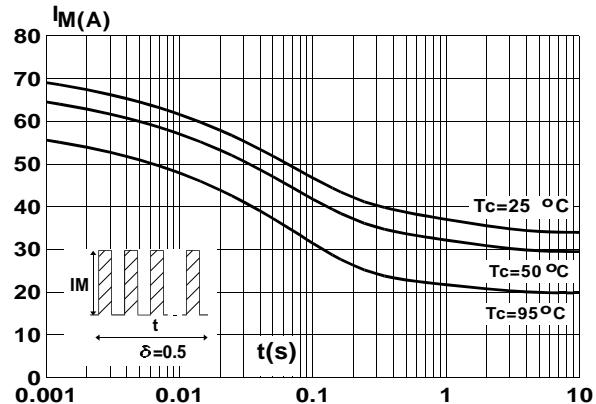


Fig.9 : Average current versus ambient temperature.
(duty cycle : 0.5) (ISOWATT220AC)

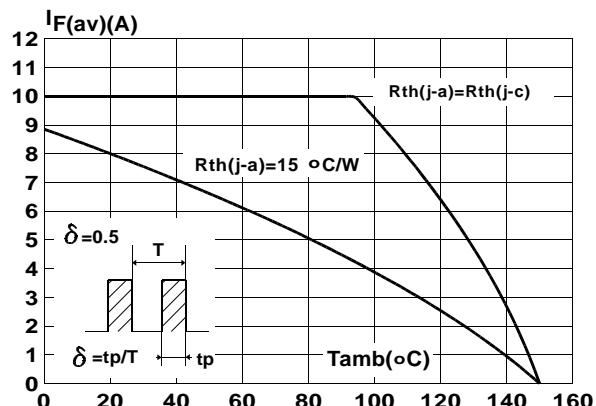


Fig.11 : Recovery charges versus dIf/dt.

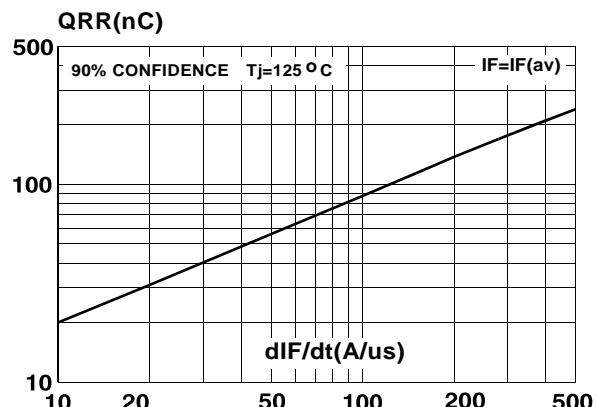
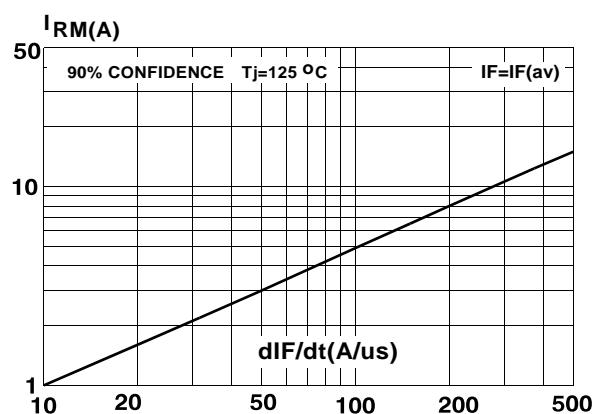
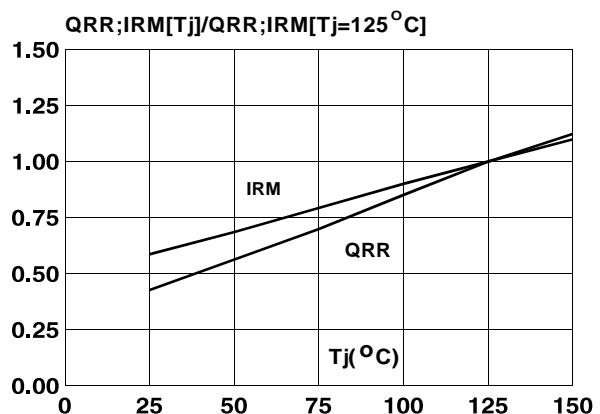
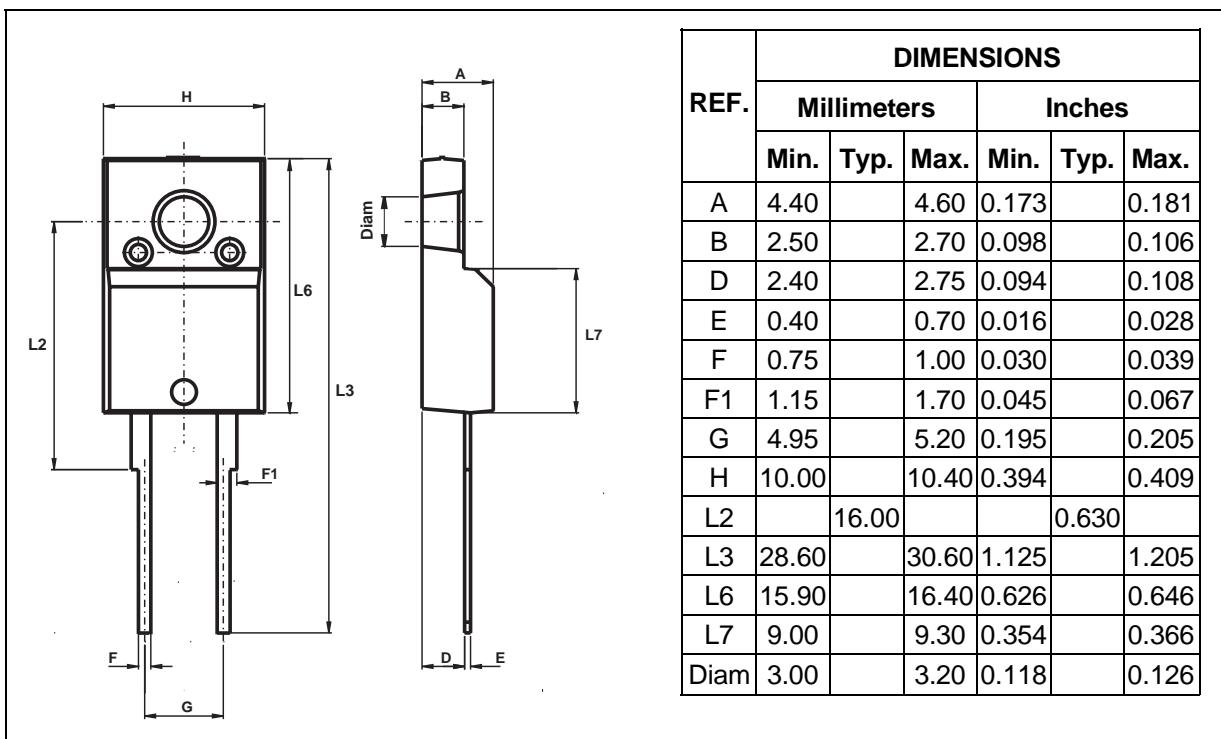


Fig.12 : Peak reverse current versus dIF/dt.**Fig.13 :** Dynamic parameters versus junction temperature.**PACKAGE MECHANICAL DATA**

ISOWATT220AC (JEDEC outline)



Cooling method : C

Marking : Type number

Weight : 2 g

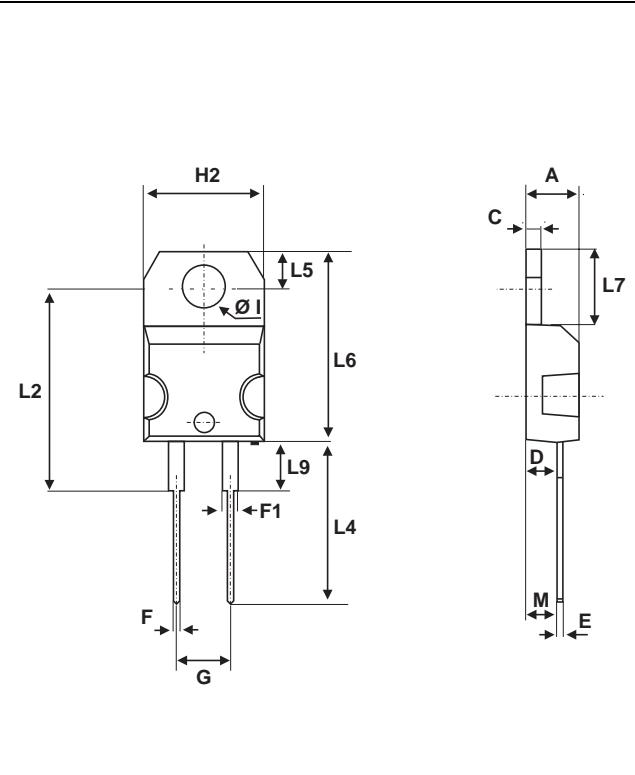
Recommended torque value : 0.55m.N

Maximum torque value : 0.70m.N

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PACKAGE MECHANICAL DATA

TO-220AC (JEDEC outline)



REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.40	4.60	0.173	0.181
C	1.23	1.32	0.048	0.051
D	2.40	2.72	0.094	0.107
E	0.49	0.70	0.019	0.027
F	0.61	0.88	0.024	0.034
F1	1.14	1.70	0.044	0.066
G	4.95	5.15	0.194	0.202
H2	10.00	10.40	0.393	0.409
L2	16.40 typ.		0.645 typ.	
L4	13.00	14.00	0.511	0.551
L5	2.65	2.95	0.104	0.116
L6	15.25	15.75	0.600	0.620
L7	6.20	6.60	0.244	0.259
L9	3.50	3.93	0.137	0.154
M	2.6 typ.		0.102 typ.	
Diam. I	3.75	3.85	0.147	0.151

Cooling method : C

Marking : Type number

Weight : 1.86 g

Recommended torque value : 0.8m.N

Maximum torque value : 1.0m.N

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